

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT6142490

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIROTSUGU KAWANAKA	03/10/2020
HIROSHI SHIRATORI	03/16/2020
SHUHO KOSEKI	03/27/2020
TADASHI FURUYA	04/02/2020
GANG HAN	04/17/2020
KIYOMI NAKAMURA	04/16/2020
RECEIVING PARTY DATA	
Name:	HITACHI METALS, LTD.
Street Address:	2-70, KONAN 1-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	108-8224
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16770756
CORRESPONDENCE DATA	
Fax Number:	(215)568-6499
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	215-568-6400
Email:	jchilson@vklaw.com
Correspondent Name:	VOLPE AND KOENIG, P.C.
Address Line 1:	30 SOUTH 17TH STREET, 18TH FLOOR
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103
ATTORNEY DOCKET NUMBER:	HITACHI7-111700917US01
NAME OF SUBMITTER:	GERALD B. HALT, JR.
SIGNATURE:	/Gerald B. Halt, Jr./
DATE SIGNED:	06/08/2020
Total Attachments: 5	

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ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by HITACHI METALS, LTD.
a corporation organized under the laws of Japan,
located at 2-70, Konan 1-chome, Minato-ku, Tokyo, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said
HITACHI METALS, LTD.
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

**POWDER MATERIAL, POWDER MATERIAL FOR ADDITIVE MANUFACTURING, AND METHOD
FOR PRODUCING POWDER MATERIAL**

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, No.PCT/JP2018/043475 filed November 27, 2018, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,
to be held and enjoyed by said HITACHI METALS, LTD.
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI METALS, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ Hirotsugu KAWANAKA	_____
2) _____ Hiroshi SHIRATORI	_____
3) <u>Shuho Koseki</u> Shuho KOSEKI	<u>Mar. 27, 2020</u>
4) _____ Tadashi FURUYA	_____
5) _____ Gang HAN	_____
6) _____ Kiyomi NAKAMURA	_____

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2)	_____ Hiroshi SHIRATORI	_____
3)	_____ Shuho KOSEKI	_____
4)	<i>Tadashi Furuya</i> _____ Tadashi FURUYA	<i>Apr 2, 2020</i> _____
5)	_____ Gang HAN	_____
6)	_____ Kiyomi NAKAMURA	_____

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3) _____ Shubo KOSEKI _____	_____
4) _____ Tadashi FURUYA _____	_____
5) _____ <i>Gang HAN</i> _____ Gang HAN _____	_____ <i>April 17, 2020</i> _____
6) _____ Kiyomi NAKAMURA _____	_____

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4) _____ Tadashi FURUYA _____	_____
5) _____ Gang HAN _____	_____
6) <u>Kiyomi Nakamura</u> _____ Kiyomi NAKAMURA _____	<u>March. 16. 2020</u>